



PRODUCT BULLETIN # 16636Generic Copy

Issue Date: 04-May-2011**TITLE:** Intent to Qualify Alternate BGA Laminate Core**PROPOSED FIRST SHIP DATE:** 29-Jul-2011**AFFECTED CHANGE CATEGORY(S):** Supplier Operation – Substrate Material**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor sales office or <ffxxxh@onsemi.com>**NOTIFICATION TYPE:**ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact <joeri.klutch@onsemi.com>.**DESCRIPTION AND PURPOSE:**

ON Semiconductor is providing this Product Bulletin (PB) of our intent to qualify alternative BGA Laminate Core material. The BGA Laminate Core is the glass fiber and epoxy resin core of laminate substrates.

This action was taken to guard against possible supply interruptions due to the recent devastating earthquake in Japan. While current indications are the supply chain is already recovering, these actions will ensure unexpected delays in supply and do not impact our ability to meet forecasted customer demand.

ON Semiconductor is working closely to monitor the supply issues, and has determined plans to mitigate risk where supply status remains unclear.

Table below shows change details for each Assembly Subcontractors with reported supply constraints.

Assembly Subcontractor	Package Affected	Primary BGA Laminate Core Material Supplier	Alternate BGA Laminate Core Material Supplier
AMKOR Korea/ Philippines	FP/P/LF/S/FC/TEPBGA	Mitsubishi Gas Chemical (MGC)	Doosan
ASE – Kaohsiung	FP/LFBGA	Mitsubishi Gas Chemical (MGC)	Doosan

Due to the risk of supply interruption caused by the Japan earthquake, some conversions may occur with less than the standard notification period.



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List of affected General Parts:

0W888-002-XTP